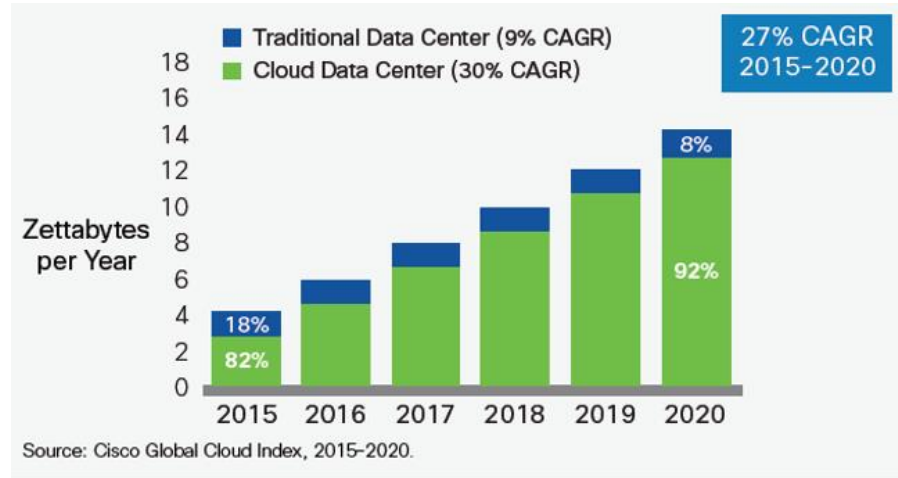


ADVANCED GERMANIUM DEVICES FOR OPTICAL INTERCONNECTS

Srinivasan Ashwyn Srinivasan

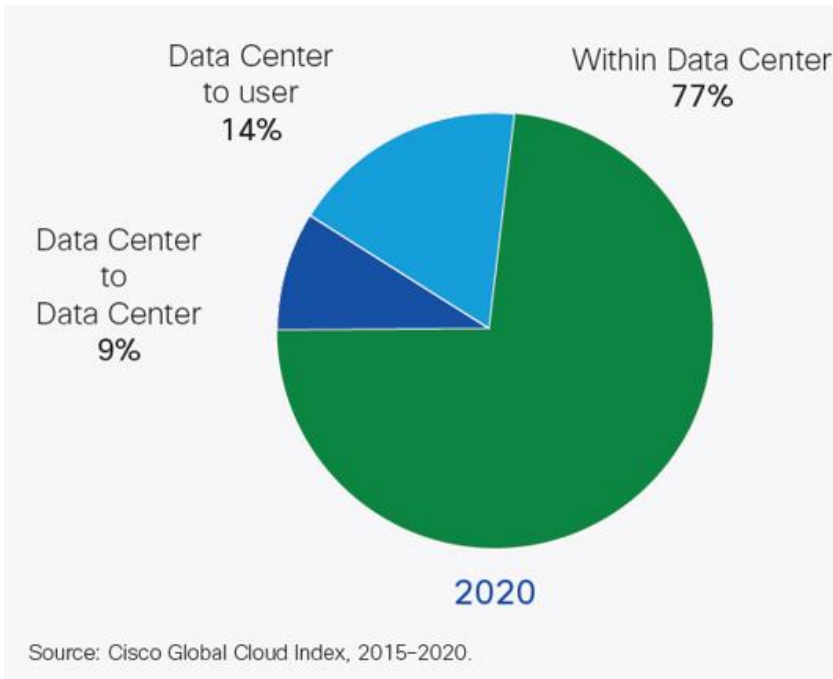
INTERNET PROTOCOL TRAFFIC

2017 This Is What Happens In An Internet Minute



1000 MB	1 Gigabyte
1000 GB	1 Terabyte
1000 TB	1 Petabyte
1000 PB	1 Exabyte
1000 EB	1 Zettabyte

INTERNET PROTOCOL TRAFFIC



A Within Data Center (77%)



Storage, production and development data, authentication

B Data Center to Data Center (9%)



Replication, CDN, intercloud links

C Data Center to User (14%)



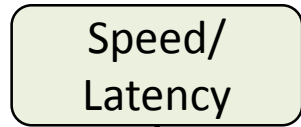
Web, email internal VoD, WebEx...

DATA CENTER: GOOGLE, MAYES COUNTY, OKLAHOMA, US

150×240 m² =
5× Anfield
(Liverpool FC)



CHALLENGES IN THE DESIGN OF THE DATA CENTERS



1. Computation speed
2. Interconnection speed

0.5s delay

 20% ↓

0.1s delay

 1% ↓

Asghari, M., & Krishnamoorthy, A. V. (2011).
Silicon photonics: Energy-efficient
communication. *Nature photonics*, 5(5), 268.



CHALLENGES IN THE DESIGN OF THE DATA CENTERS

Speed/
Latency

1. Computation speed
2. Interconnection speed

Cost

1. Equipment costs
2. Administering the data centers

0.5s delay

Google 20% ↓

0.1s delay

amazon 1% ↓



Krishnamoorthy, A. V., Goossen, K. W., Jan, W., Zheng, X., Ho, R., Li, G., ... & Schwetman, H. (2011). Progress in low-power switched optical interconnects. *IEEE Journal of selected topics in quantum electronics*, 17(2), 357-376.

Asghari, M., & Krishnamoorthy, A. V. (2011). Silicon photonics: Energy-efficient communication. *Nature photonics*, 5(5), 268.



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Power
Consumption

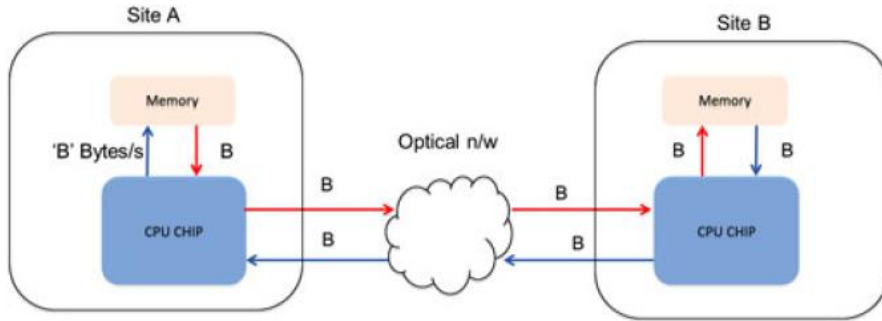
1. Compute node
2. Data storage node
3. Switch node
4. Heating, ventilation and air conditioning (HVAC)



<https://www.independent.co.uk/environment/global-warming-data-centres-to-consume-three-times-as-much-energy-in-next-decade-experts-warn-a6830086.html>

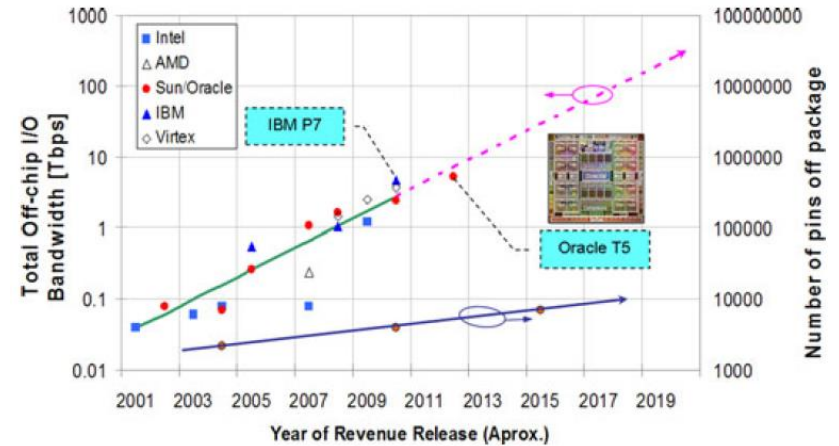


ELECTRICAL INTERCONNECTS

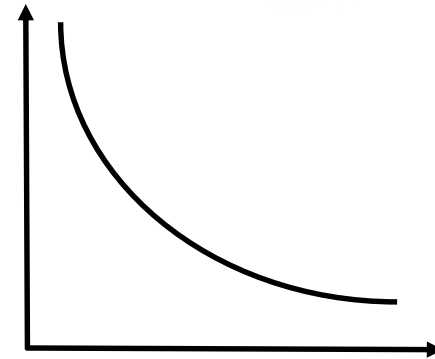


For long distance communication (> 3 m), power consumption is significant due to:

- 1) Skin effect losses
- 2) Dielectric losses



Latency

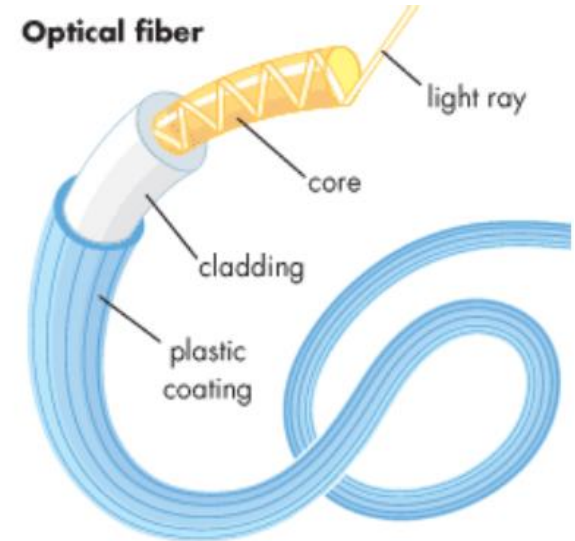
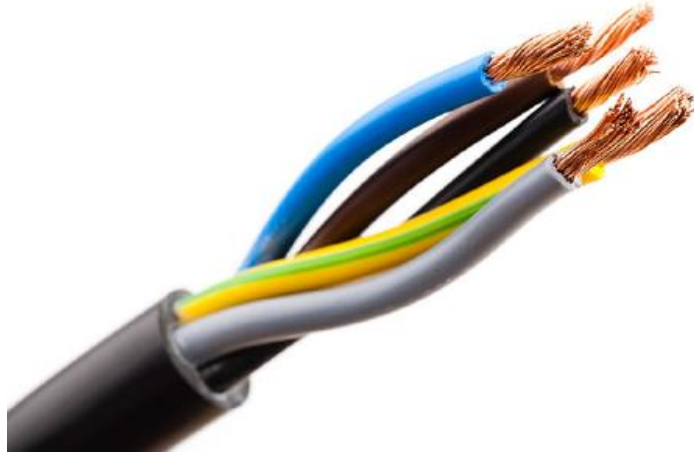


Power consumption

Schwetman, H., Patel, A., Robinson, L., Zheng, X., Wood, A., & Krishnamoorthy, A. V. (2016). An Energy-Efficient Optical Interconnect Architecture for Bandwidth-Balanced Systems. *Journal of Lightwave Technology*, 34(12), 2905-2919.

Krishnamoorthy, A. V., Thacker, H. D., Torudbakken, O., Müller, S., Srinivasan, A., Decker, P. J., ... & Dignum, M. (2017). From Chip to Cloud: Optical Interconnects in Engineered Systems. *Journal of Lightwave Technology*, 35(15), 3103-3115.

ELECTRICAL → OPTICAL INTERCONNECTS



© 2006 Encyclopædia Britannica, Inc.

Requirements for optical interconnects:

High Speed

100-400 Gbps

Low equipment
Cost

<1 \$/Gbps

Low Power
Consumption

<10 pJ/bit

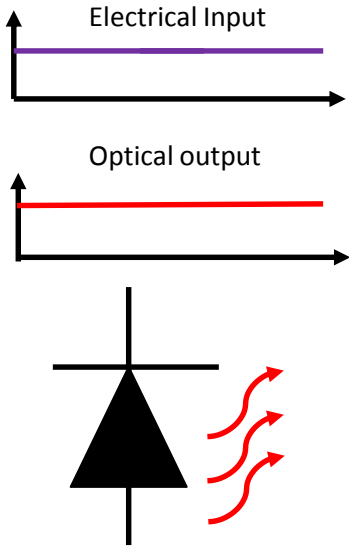
High Temp
operation

Large optical bandwidth
of individual devices

OPTICAL INTERCONNECT

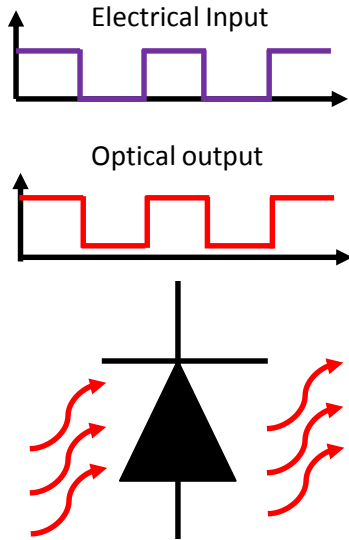
Light, instead of electricity, is used to carry information

Light source



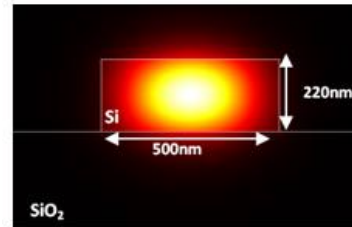
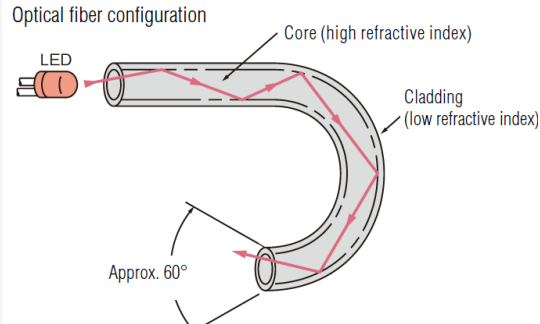
Let there be light!!!

Modulator



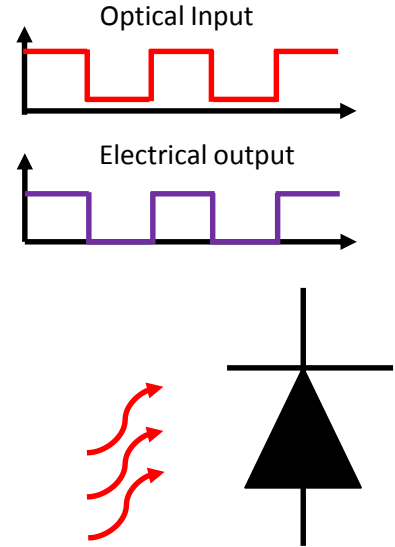
Convert electrical signal to optical signal.

Transport medium



Manipulate light by routing/filtering.
Medium for light propagation

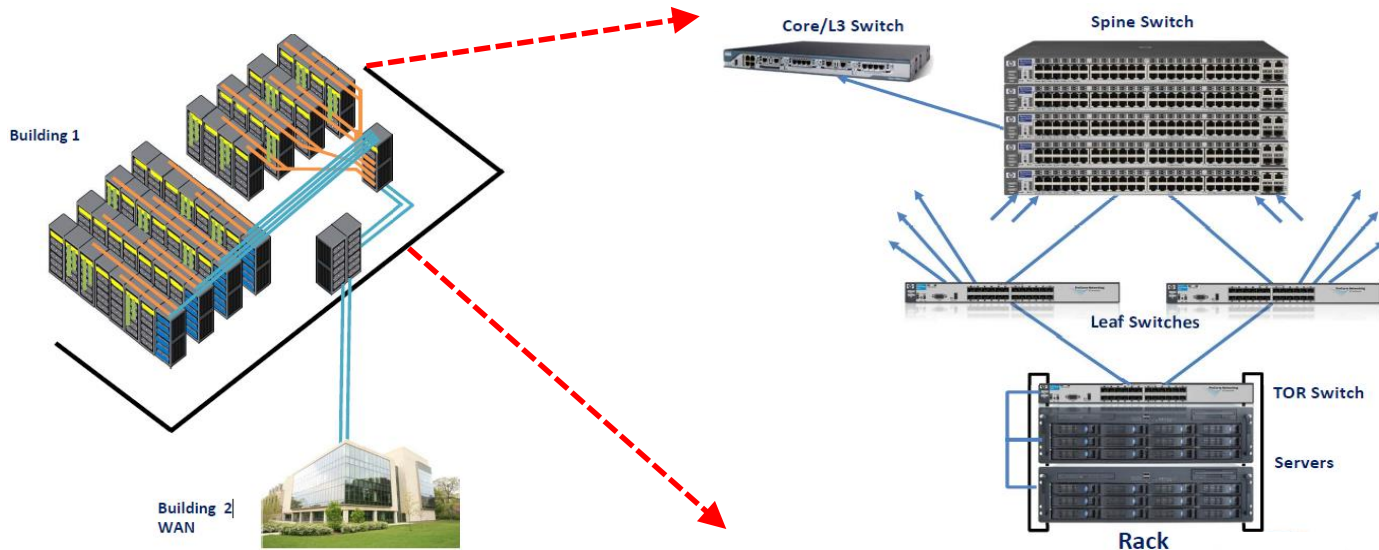
Photodetector



Convert optical signal to electrical signal.

OPTICAL INTERCONNECTS IN DATA CENTERS

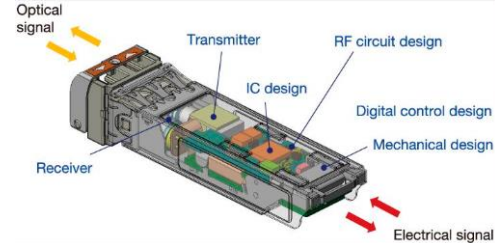
MMF- Multi mode fiber
SMF - Single mode fiber



	Server to TOR (<3 m)	TOR to Leaf (3-20 m)	Leaf to Spine (400-2000 m)	Spine to Core (500-2000 m)
Deployed today	10G Cu	40G MMF	40G MMF	40G SMF
Being upgraded	25G Cu	100G SMF	100G SMF	100G SMF
For future	50/100G Cu	400G SMF	400G SMF	400G SMF

OPTICAL TRANSCEIVER

Optical transceiver → Optical transmitter and receiver
A component used to transmit-receive optical signals.



100GbE QSFP28
PSM4



100GbE QSFP28
CWDM4



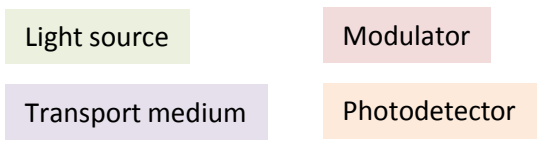
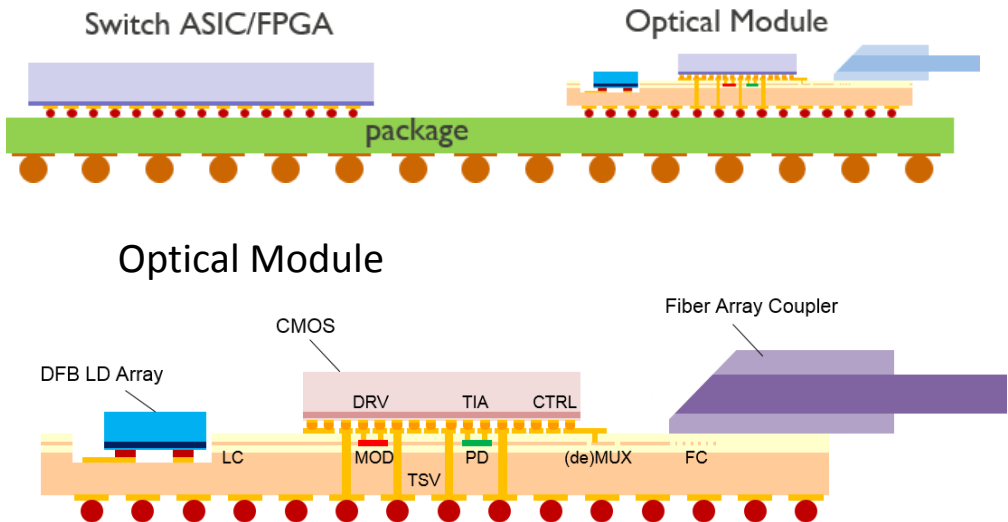
100GbE QSFP28
PSM4



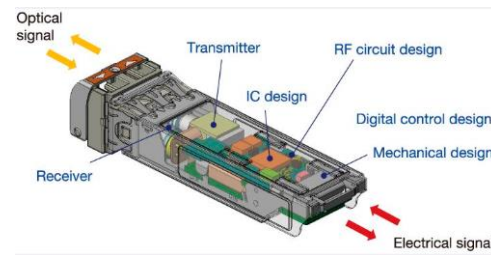
100GbE QSFP28
CWDM4

OPTICAL TRANSCEIVER

Cross-section



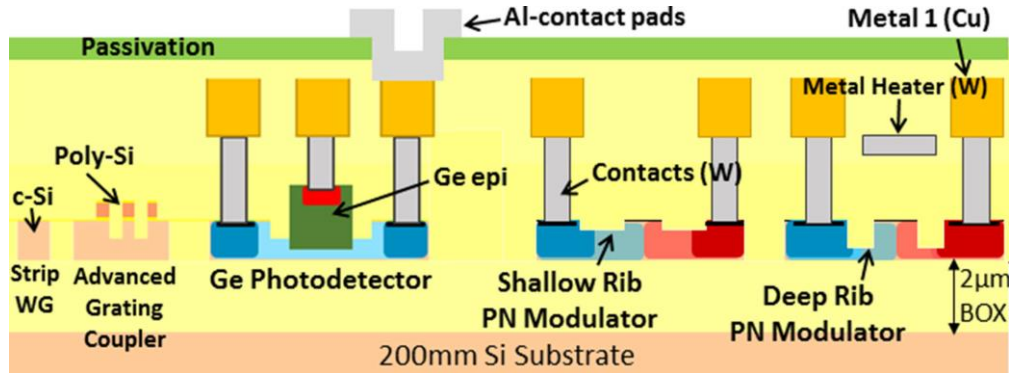
Cartoon



DFB LD Array	Laser array
LC	Light coupler
MOD	Modulator
PD	Photodetector
(de)MUX	(de)Multiplexer
FC	Fiber coupler
TSV	Through Silicon Vias
DRV	Electrical driver
TIA	Transimpedance Amplifier
CTRL	Controller circuit

SILICON PHOTONICS

Material platform based on Si to realize optical transceivers



imec's 200mm Silicon photonics platform

Pantouvaki, M., Srinivasan, ... & Absil, P. (2017). *Journal of Lightwave Technology*, 35(4), 631-638.

Devices	Material	Status
Photodetector	Ge	Yes
Micro Ring modulator (MRR)	Si	Yes
Mach Zehnder Modulator (MZM)	Si	Yes
Grating couplers/ Light coupler/ Fiber couplers	Si	Yes
(de)MUX filters	Si	Yes
Light source (Laser diode)	??	None

Need for monolithically integrated light source!!

GERMANIUM DEVICES FOR OPTICAL INTERCONNECTS

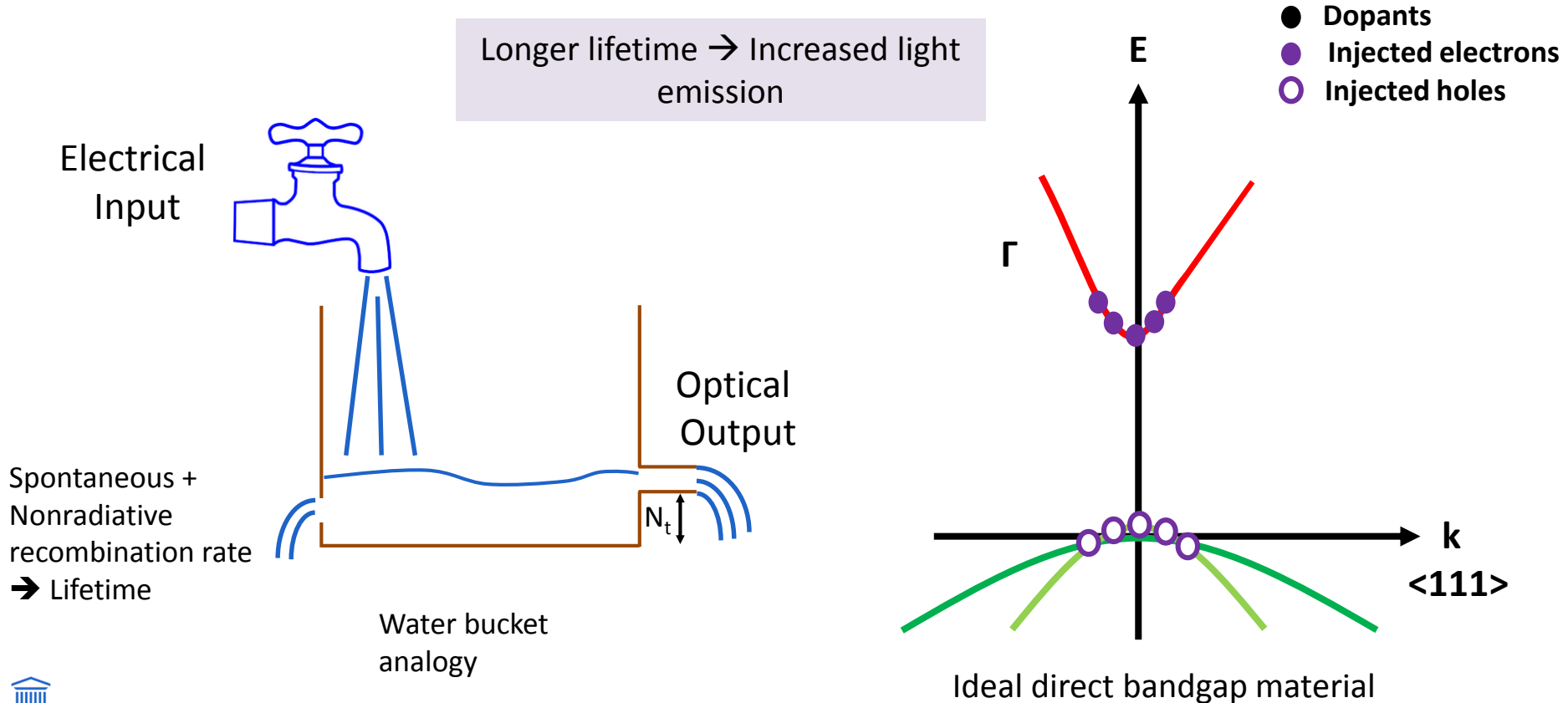
Active medium	Temp (K)	J_{th} (P_{th}) – current density	λ (nm)
III-V Quantum dot	300	< 1 kA/cm ²	1310
P-doped Ge	300	280-510 kA/cm ²	1576-1650

Modulators	Opt. BW	Speed	Power consumption
Si MZM	> 80 nm	22 GHz	750 fJ/bit
Si MRR	< 0.2 nm	47 GHz	12.8 fJ/bit
Ge FKE EAM	~ 30 nm	40 GHz	60 fJ/bit
Ge QCSE EAM	~ 20 nm	23 GHz	16 fJ/bit

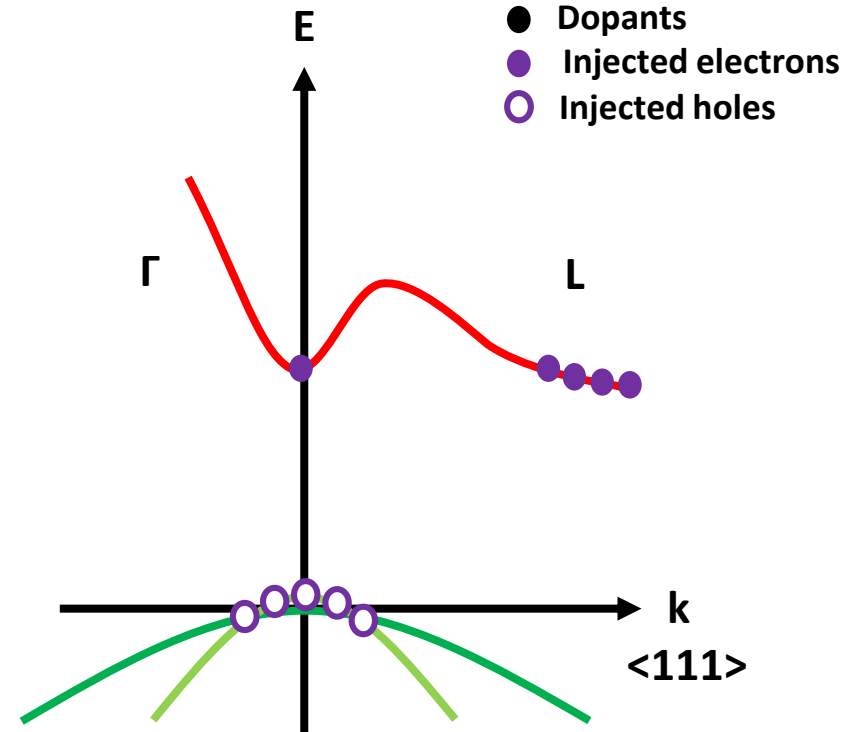
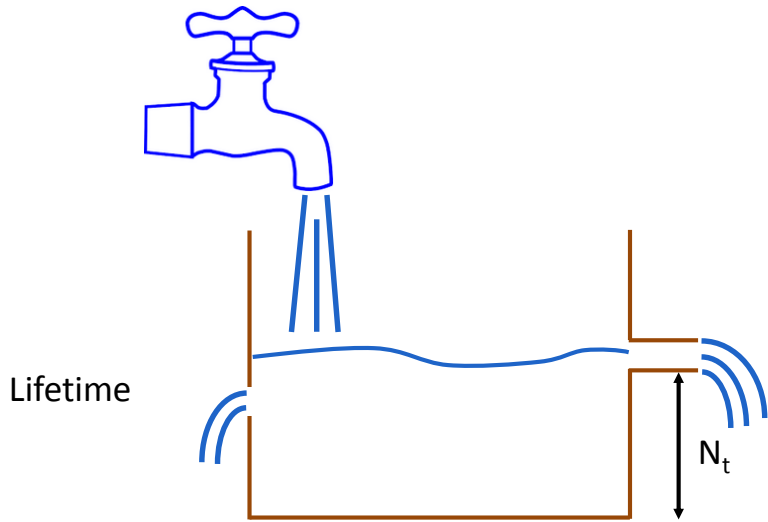
Evaluate Ge modulators and Ge Laser Diodes are technologically viable for Optical Interconnect applications while addressing:

- 1) Power consumption:
 - a) <50 fJ/bit for Ge modulator
 - b) <10 kA/cm² for Ge laser
- 2) Speed:
 - a) ≥50 GHz
- 3) Operating wavelength:
 - a) C and L band
 - b) If feasible, O band

LIGHT EMISSION FROM DIRECT BANDGAP MATERIAL



LIGHT EMISSION EFFICIENCY FROM UNDOPED GE

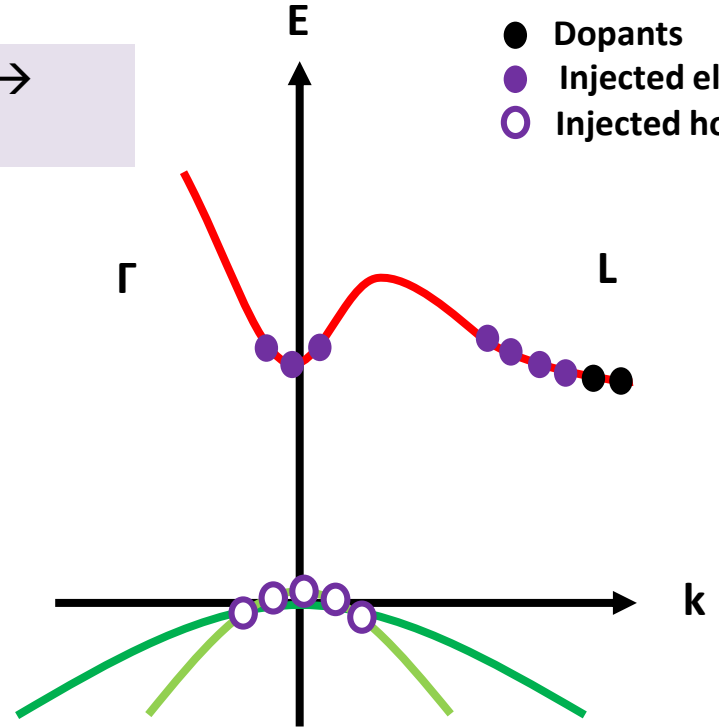
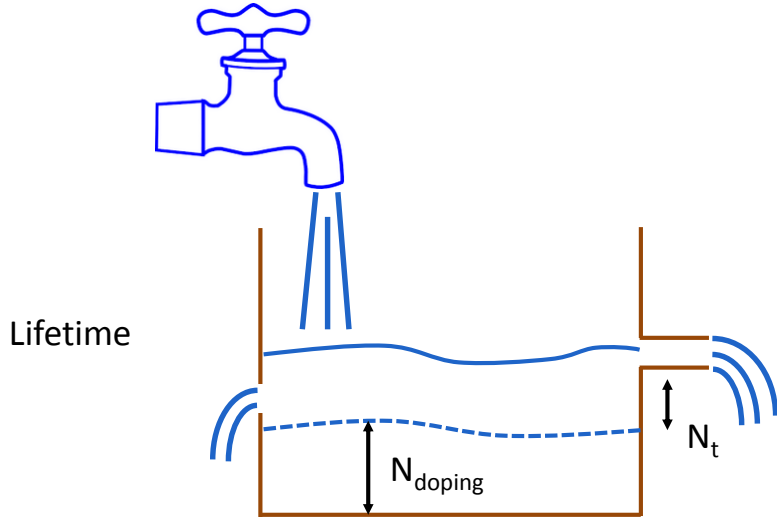


Undoped and unstrained Ge

LIGHT EMISSION EFFICIENCY FROM DOPED GE

High doping, longer lifetime \rightarrow
Increased light emission

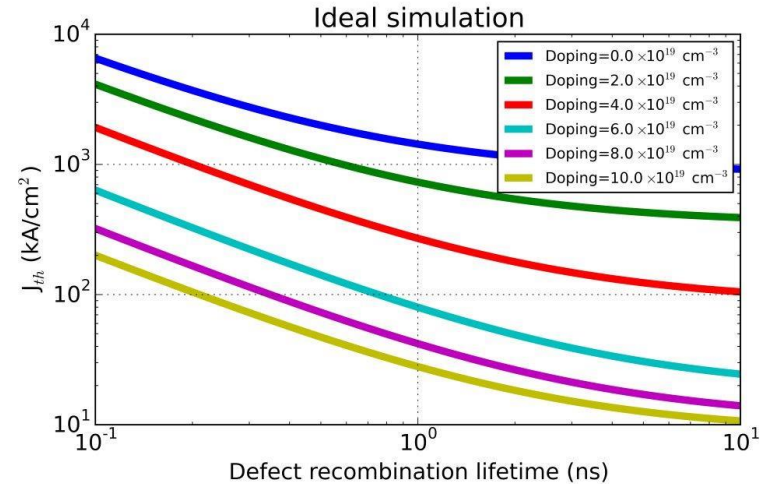
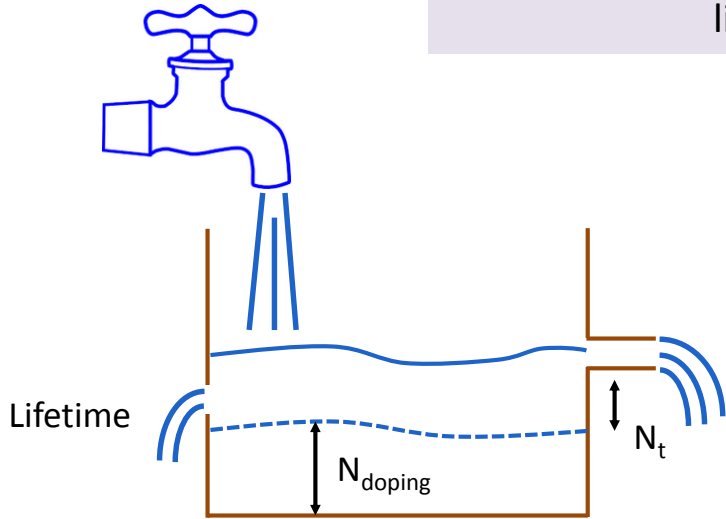
- Dopants
- Injected electrons
- Injected holes



0.2 % biaxially strained and n-type
doped Ge

GE LASER: REQUIREMENTS

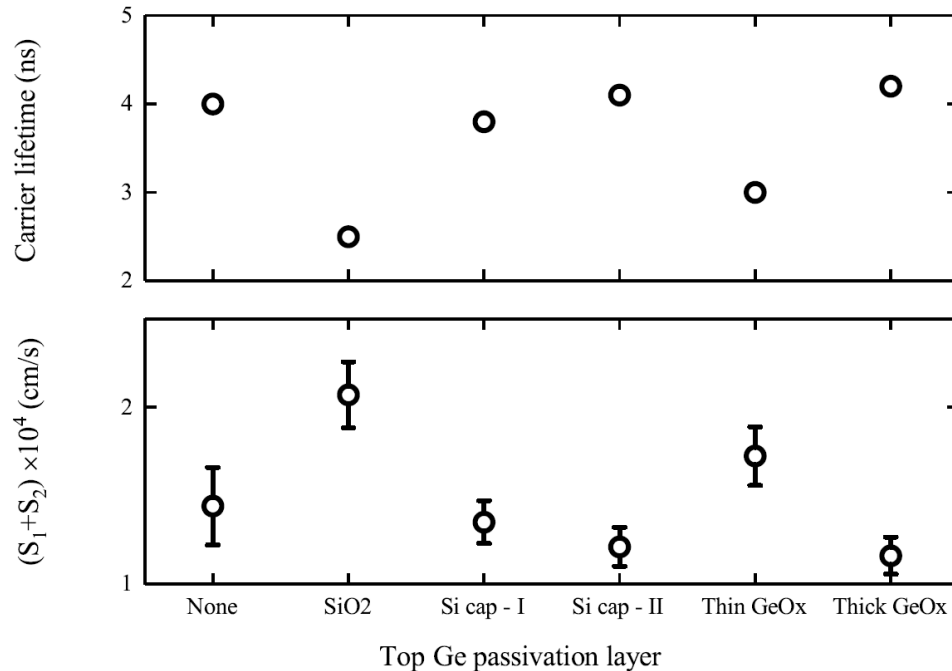
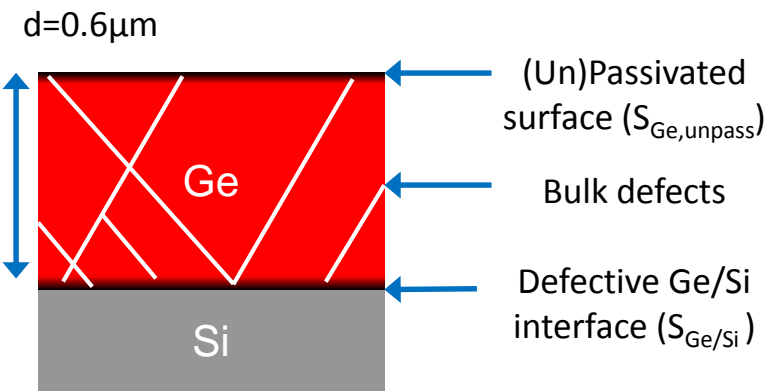
High doping, longer lifetime \rightarrow Increased light emission



Design target for $J_{\text{th}} < 10$ kA/cm²:

1. Lifetime > 10 ns.
2. Doping level as high as 1×10^{20} cm⁻³.

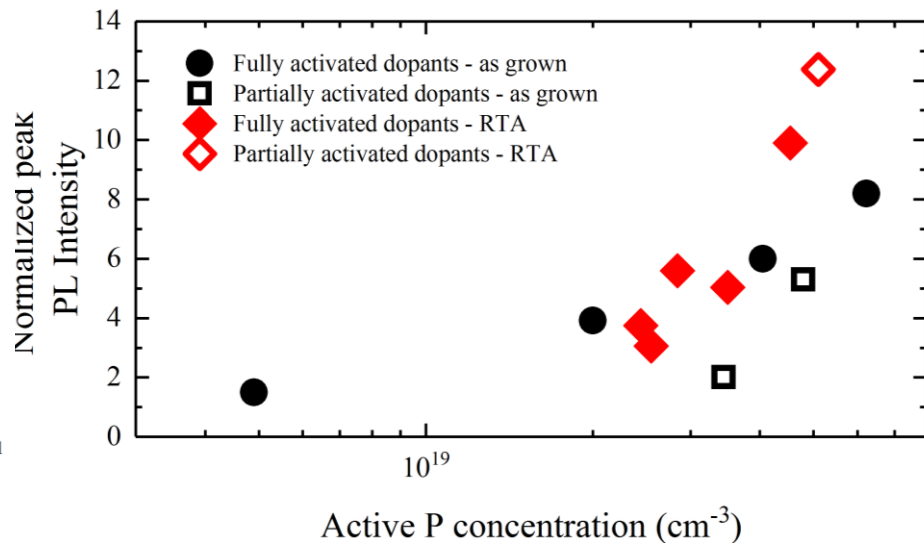
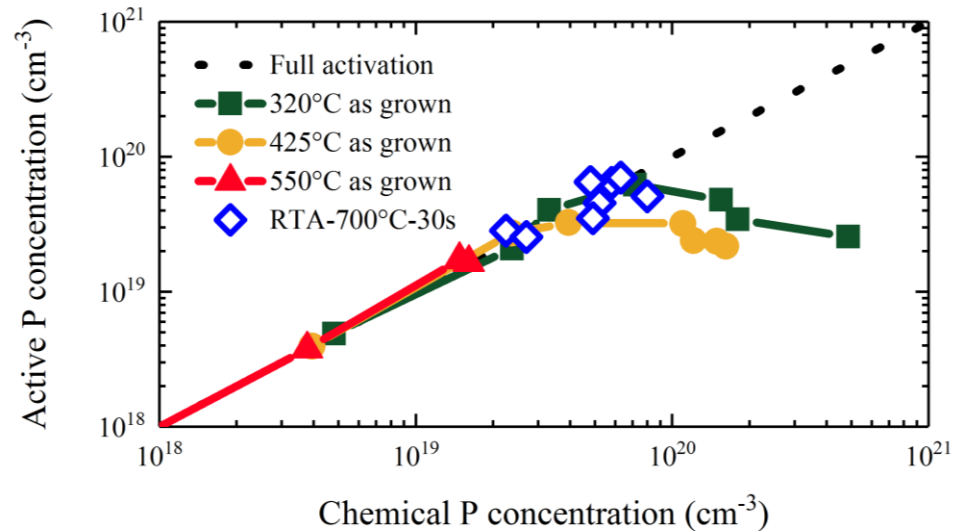
CARRIER LIFETIME IN UNDOPED GE



$$\frac{1}{\tau_{\text{carrier}}} = \frac{1}{\tau_{\text{Bulk}}} + \frac{S_{\text{Ge,unpass}} + S_{\text{Ge/Si}}}{d}$$

- SiO_2 passivation layer \rightarrow lowest lifetime
- Si cap or Thick GeOx \rightarrow longest carrier lifetime of 4.3 ns.
- Measured lifetime < targeted 10 ns.

P-DOPED GE ON 1 μM GE VIRTUAL SUBSTRATE

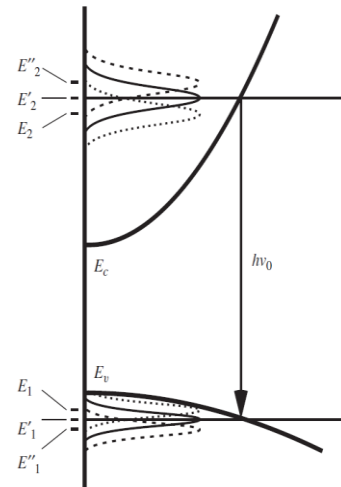
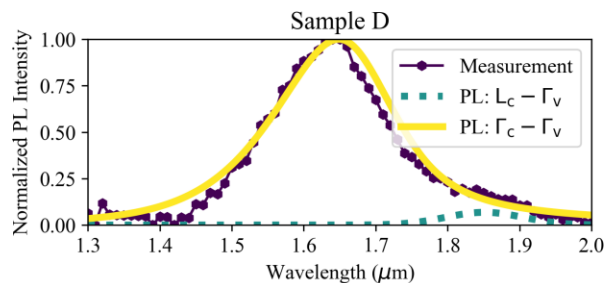
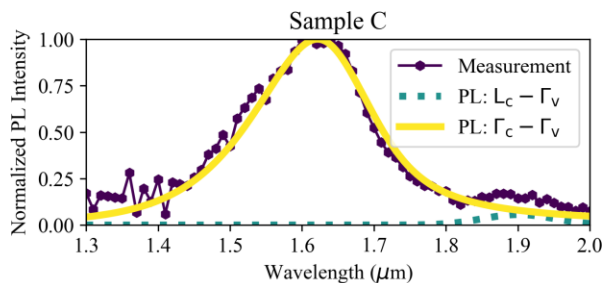
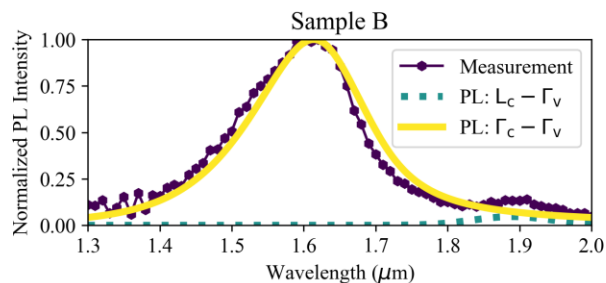
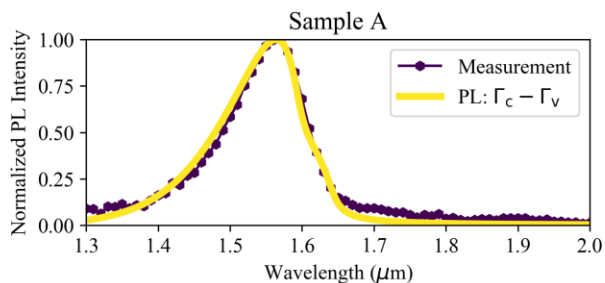


Highest active P concentration:

- As grown $\rightarrow 6.2 \times 10^{19}$ cm^{-3}
- Rapid thermal annealed $\rightarrow 5.9 \times 10^{19}$ cm^{-3}

Less than targeted 1×10^{20} cm^{-3}

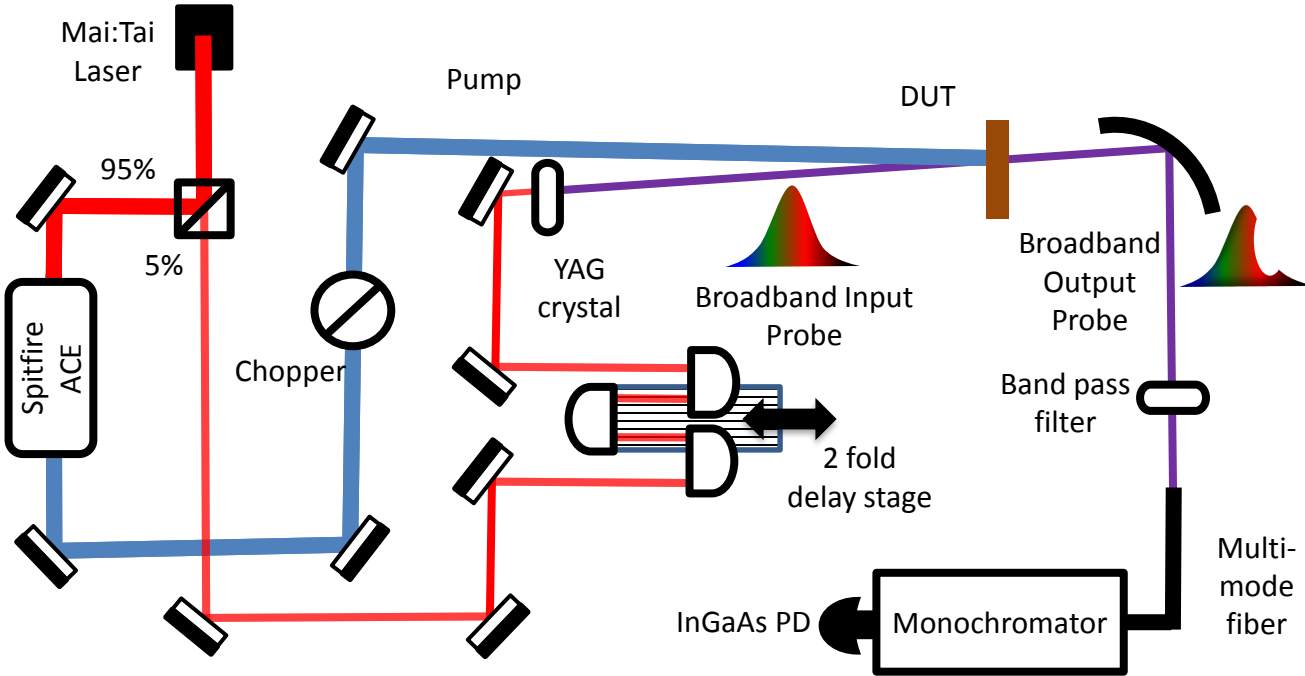
CARRIER SCATTERING STUDY: PL SPECTROSCOPY



Carrier scattering induced broadening →
broadened PL spectrum → caused by dopants

Name	Active P (cm ⁻³)	Γ _{opt}
Sample A	0.0×10 ¹⁹	8 meV
Sample B	2.65×10 ¹⁹	47.5 meV
Sample C	4.5×10 ¹⁹	50 meV
Sample D	5.35×10 ¹⁹	45 meV

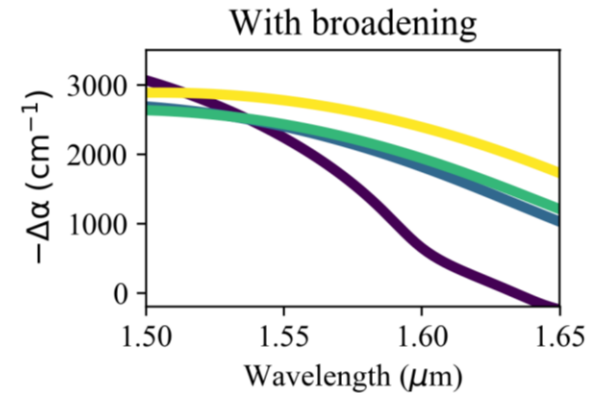
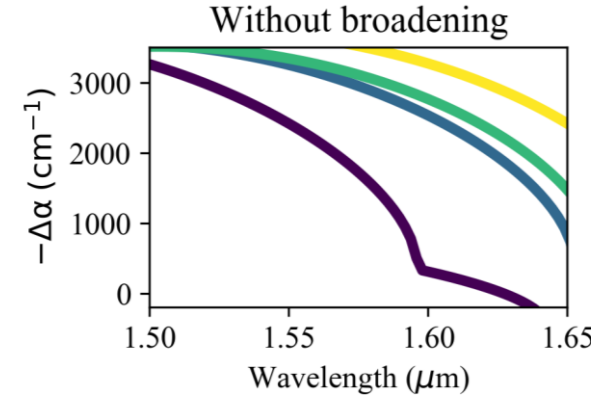
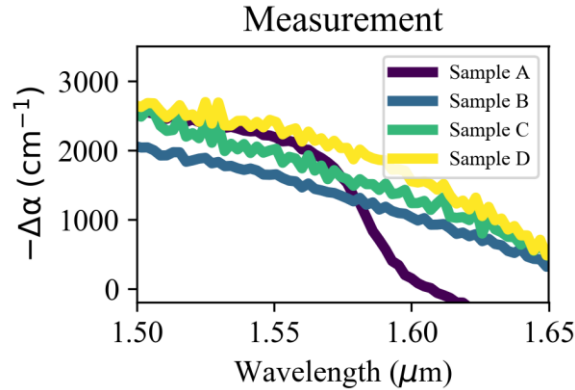
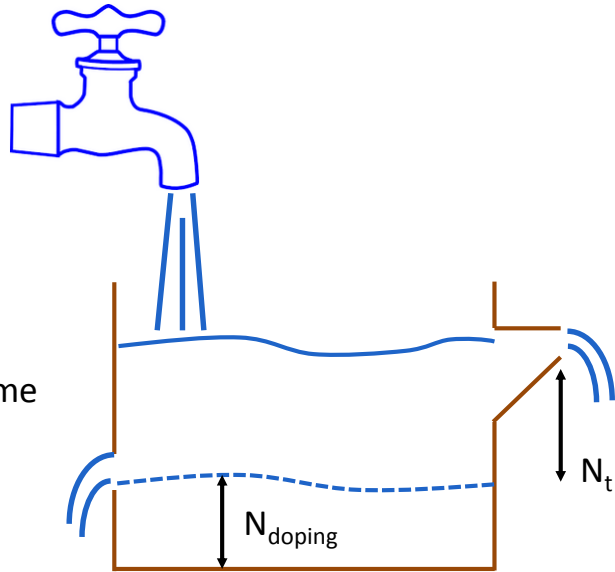
TRANSIENT ABSORPTION SPECTROSCOPY (TAS)



Experiment Condition	Value
Pump wavelength	$\approx 1.3 \mu\text{m}$
Ave Pump Intensity	28-140 mW/cm ²
Probe Wavelength	1.5-1.7 μm
$N_{\text{ex,Pump}}$	$(1.5-8) \times 10^{18} \text{ cm}^{-3}$

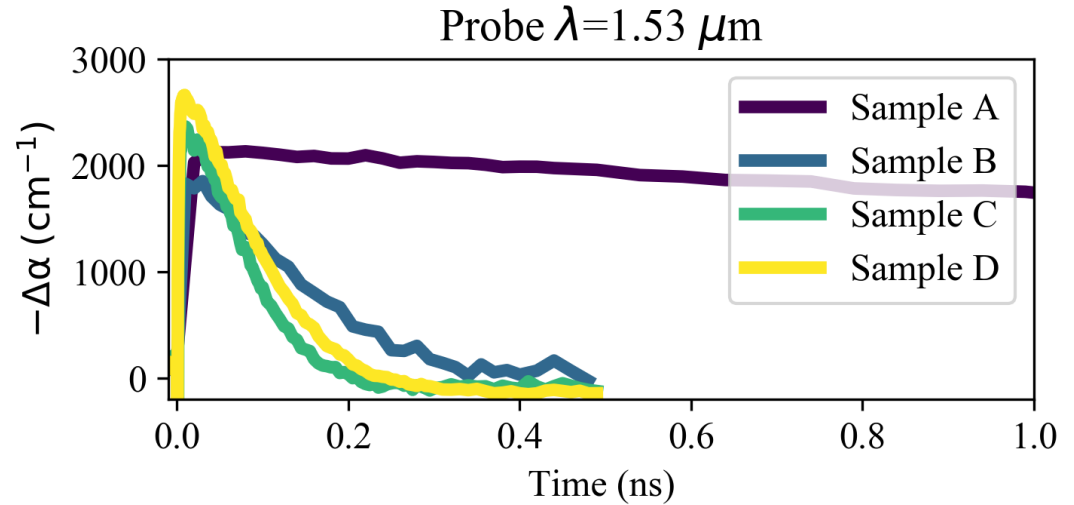
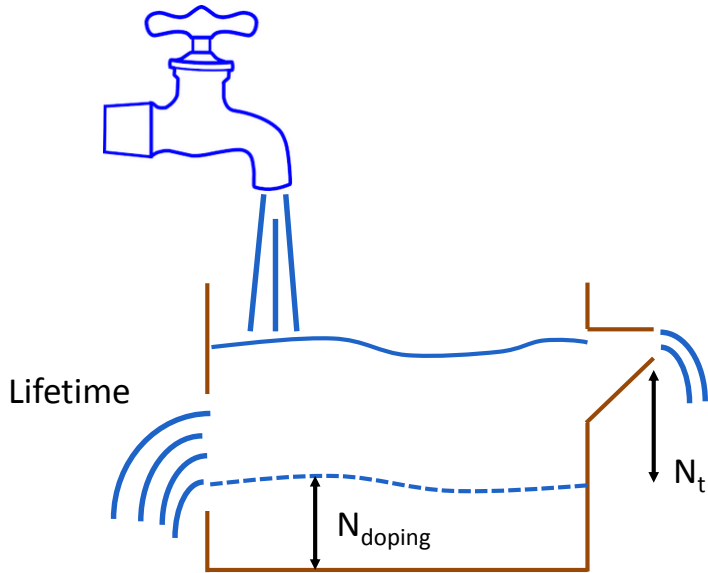
- The measurement is performed in transmission mode.
- Change in absorption coefficient of the probe beam as a function of time is tracked.

CARRIER SCATTERING STUDY: TRANSIENT ABSORPTION SPECTROSCOPY



Carrier scattering induced broadening \rightarrow suppressed and broadened OBE spectrum \rightarrow caused by dopants.

CARRIER SCATTERING STUDY: TRANSIENT ABSORPTION SPECTROSCOPY

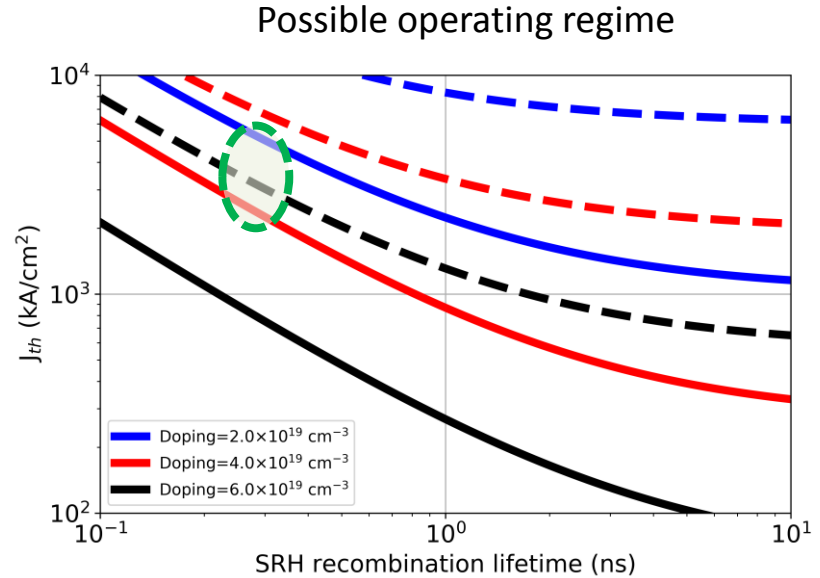
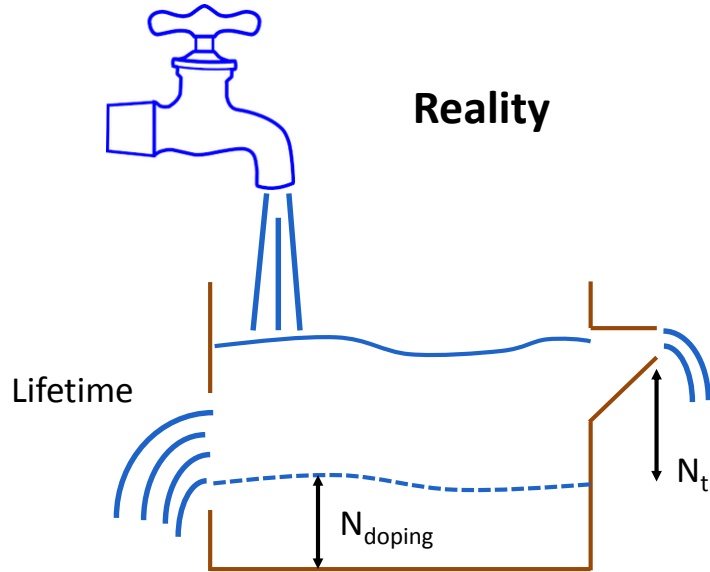


Lifetime in undoped Ge \rightarrow 3-4 ns

Lifetime in doped Ge \rightarrow < 0.3 ns

Reduced lifetime due to dopants.

GE LASER: CONCLUSION

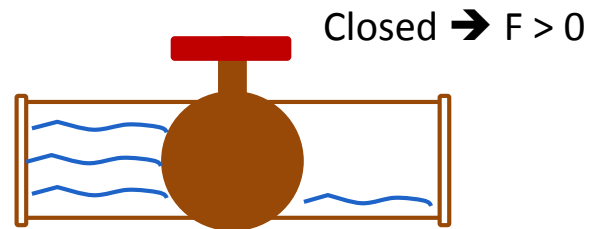
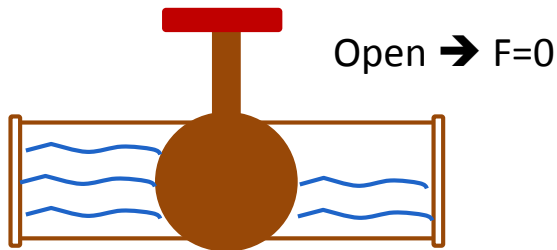


Solid line → with no linewidth broadening.
 Dotted line → with linewidth broadening $\Gamma_{opt} = 45$ meV.

Difficult to demonstrate an energy efficient P-doped Ge laser for optical interconnect applications.

ELECTRO-ABSORPTION MODULATOR (EAM)

Pipe and valve analogy



Ideal scenario:

Open → no loss

Closed → ∞ loss

Reality:

Open → Insertion loss (IL)

Closed → Extinction Ratio (ER)

Factors determining the performance of a modulator:

FOM = ER/IL

∞

Switching speed

> 40 GHz

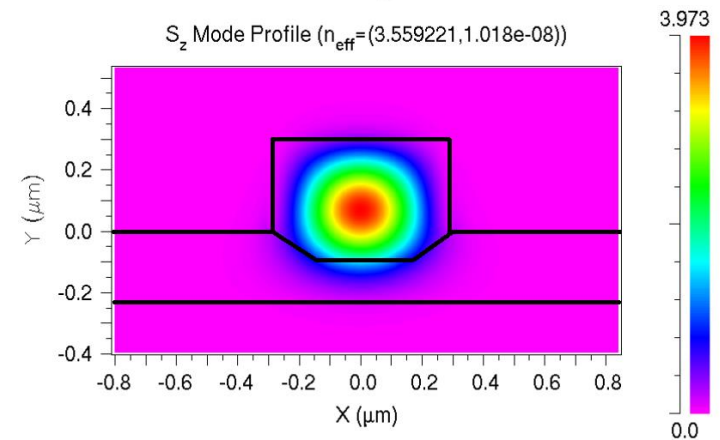
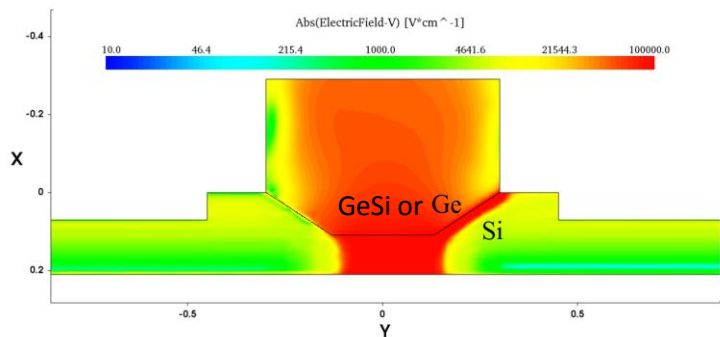
Power
Consumption

< 60 fJ/bit

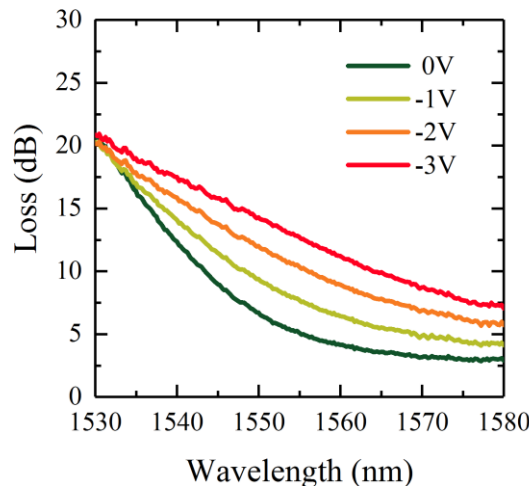
Operating
wavelength

1530-1570 nm

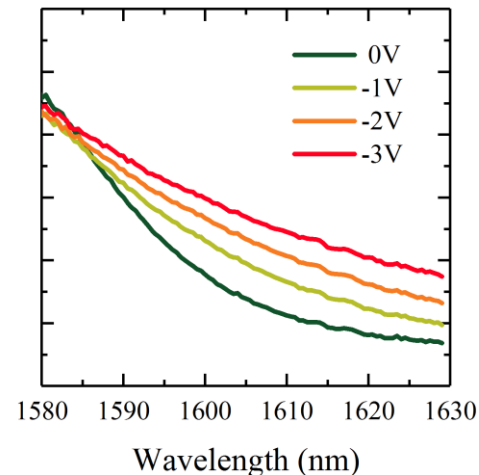
GeSi FRANZ-KELDYSH EFFECT EAM: STATIC PERFORMANCE - I



GeSi FKE EAM

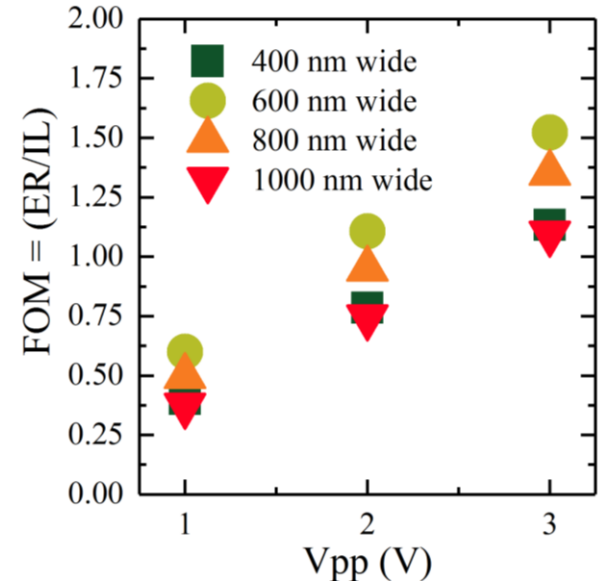
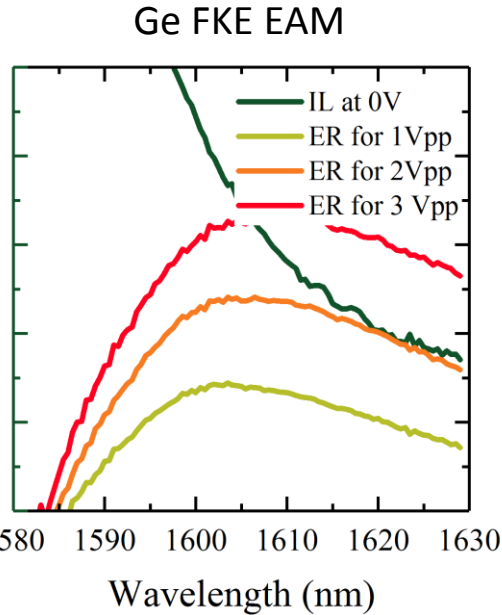
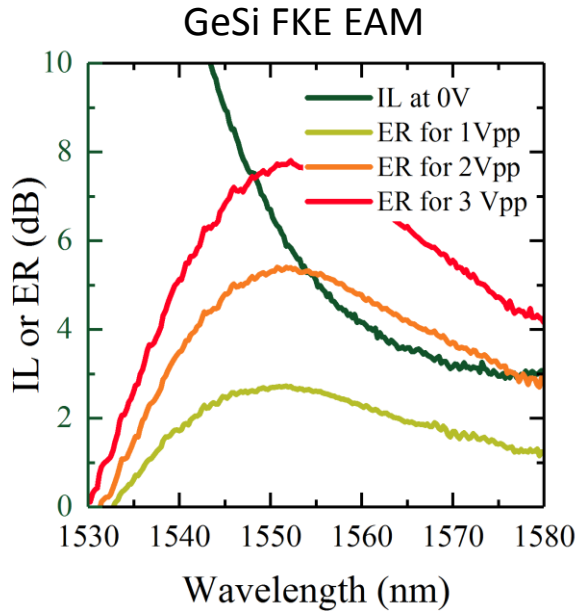


Ge FKE EAM



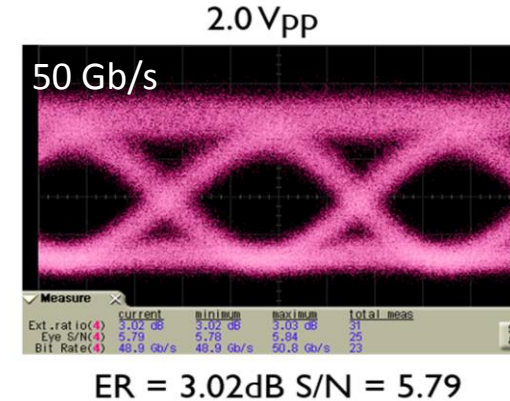
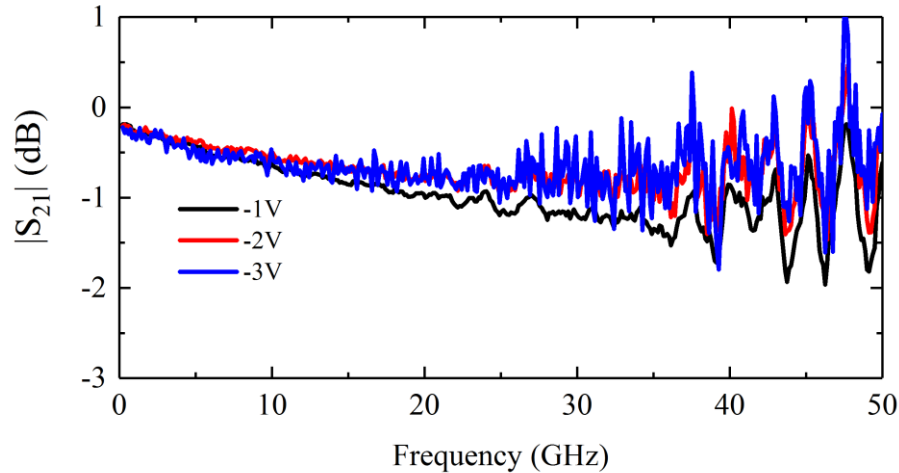
Electrical voltage modulates the intensity of light at the output of the waveguide.

GeSi FRANZ-KELDYSH EFFECT EAM: STATIC PERFORMANCE - II



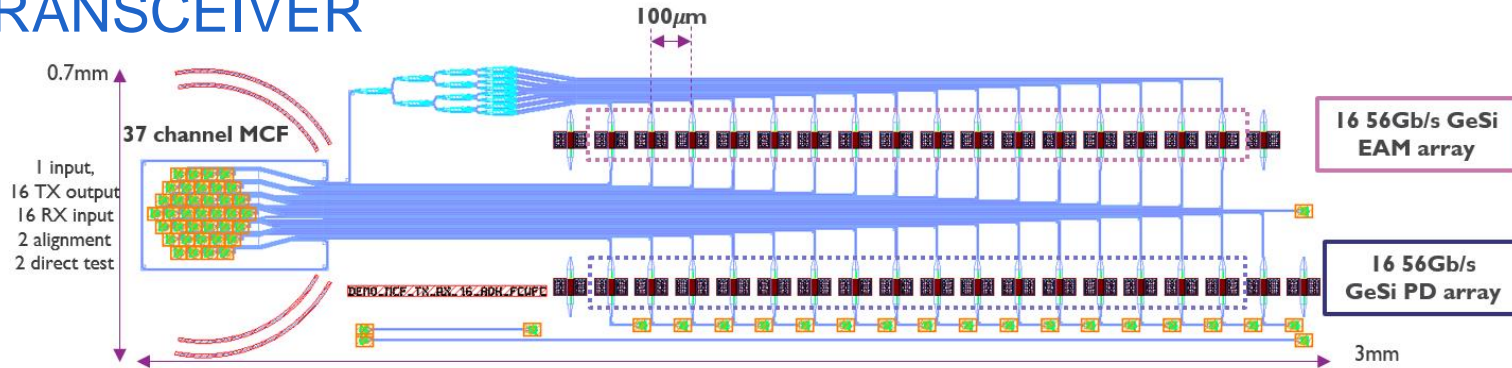
Low FOM due to indirect bandgap material.

GESI FRANZ-KELDYSH EFFECT EAM: DYNAMIC PERFORMANCE



Enables 50 Gb/s NRZ-OOO modulation due to compact geometry and low junction capacitance. Power consumption 29 fJ/bit.

DEMONSTRATORS USING GESI EAM: 896 GB/s TRANSCIVER



GeSi EAM array

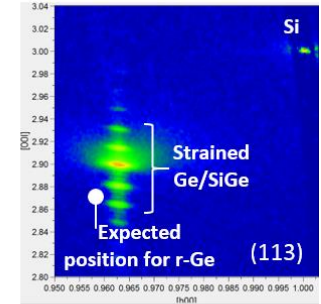
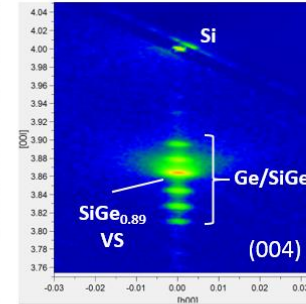
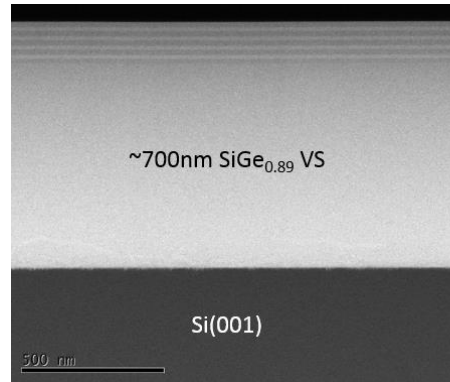
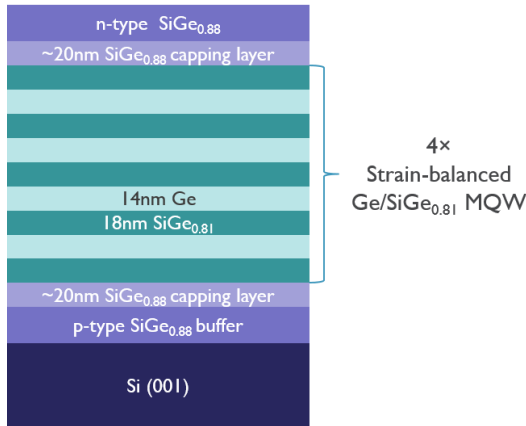
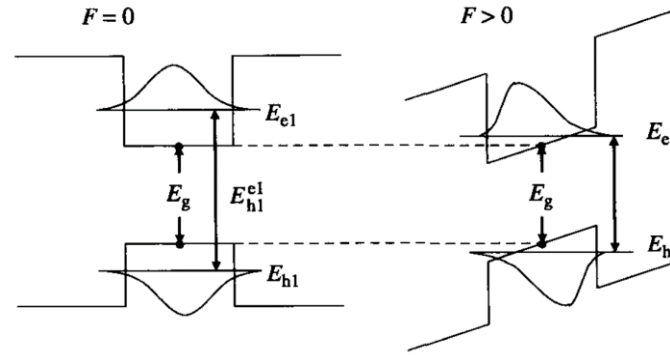


GeSi PD array

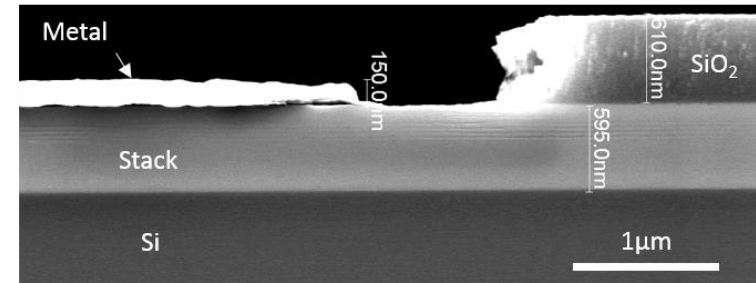
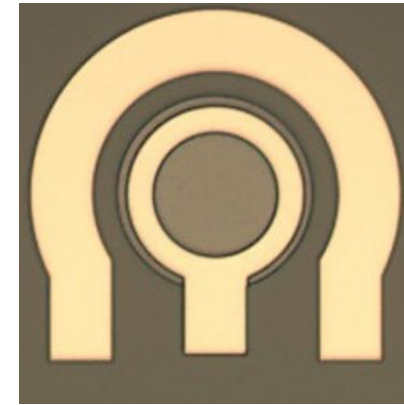
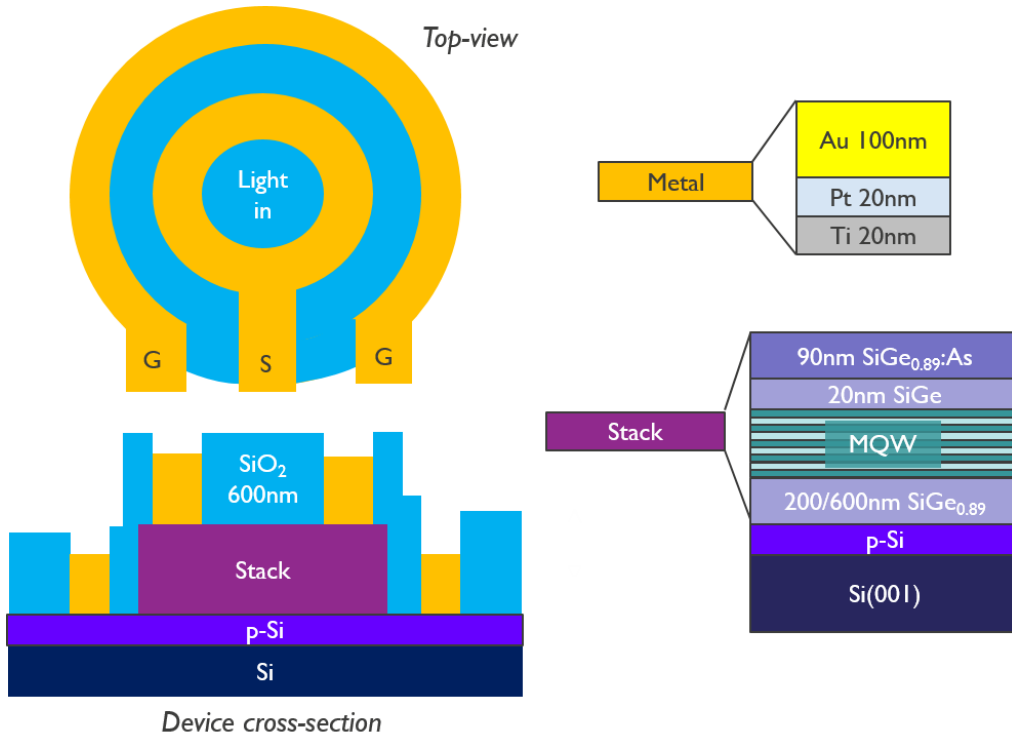


GeSi QUANTUM CONFINED STARK EFFECT EAM

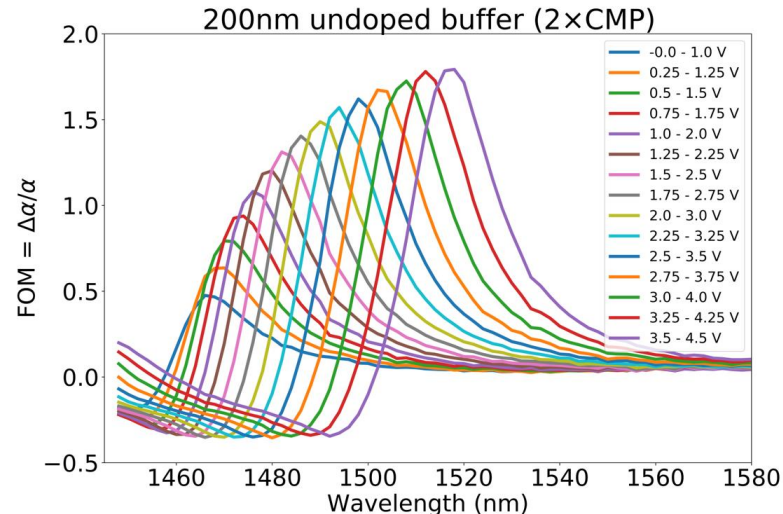
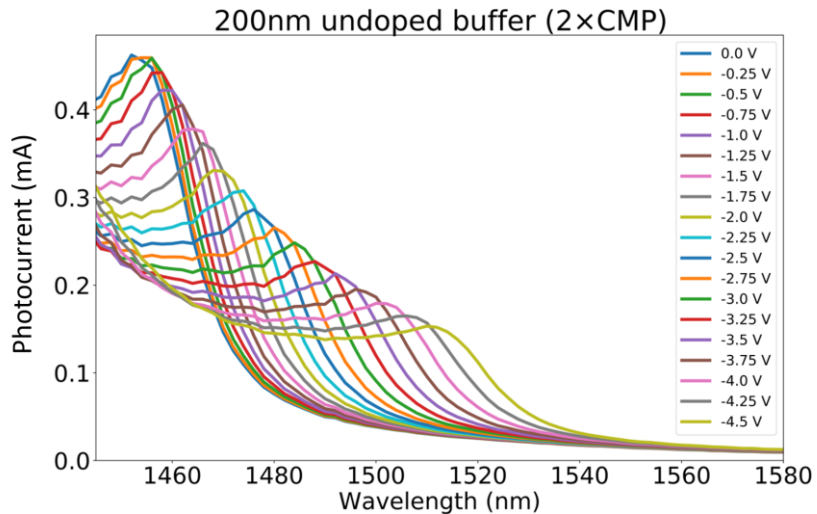
To boost the FOM of GeSi FKE EAM \rightarrow GeSi QCSE EAM.



GE/SI QUANTUM CONFINED STARK EFFECT EAM



GESI QUANTUM CONFINED STARK EFFECT EAM



FOM ($\Delta\alpha/\alpha$) \approx 1.75 for 1 V swing \rightarrow $> 2\times$ better than Ge FKE EAM.

Future perspectives:

1. Demonstrate waveguide integrated device \rightarrow reevaluate FOM.
2. Demonstrate demonstrating at speeds >50 GHz.

CONCLUSION: ADVANCED GE DEVICES FOR OPTICAL INTERCONNECTS

- *P-doped Ge laser on Si* → Difficult to achieve energy efficient laser due to:

	Carrier Lifetime	Doping Level	Linewidth Broadening	J_{th} (kA/cm ²)
Target	> 10 ns	1×10^{20} cm ⁻³	< 10 meV	< 10
Reality	< 0.3 ns	5.35×10^{19} cm ⁻³	≥ 45 meV	> 1000

- *Ge based electro absorption modulator:*

Modulators	FOM ($\Delta\alpha/\alpha$)	Opt. BW	Speed	Power
Si MZM	0.47 for 2.5 Vpp	>80 nm	22 GHz	750 fJ/bit
Si MRR	0.72 for 1.5 Vpp	<0.2 nm	47 GHz	12.8 fJ/bit
Ge FKE EAM	1.2 for 3 Vpp	~ 30 nm	40 GHz	60 fJ/bit
Ge QCSE EAM	1.46 for 5 Vpp	~ 30nm	23 GHz	16 fJ/bit
GeSi FKE EAM (This work)	0.93 for 2 Vpp	~ 30 nm	>50 GHz	29 fJ/bit
Ge QCSE EAM (This work)	1.75 for 1 Vpp	~ 20nm	??	??

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